In the Claims:

CLAIMS 1-28 (Cancel)

CLAIM 29 (Previously Presented) A method of fabricating an electrical interconnection element having a contact tip structure, comprising:

forming a contact tip structure on a sacrificial substrate;

prior to constructing the contact tip structure, providing a texture in an area of the sacrificial substrate, wherein the contact tip structure is formed on the area of the sacrificial substrate which is formed with the texture;

attaching an electrical interconnection element to the contact tip structure to form a first structure having the electrical interconnection element and the contact tip structure; and

removing the contact tip structure from the sacrificial substrate wherein the first structure is compliant after said removing of the contact tip structure.

CLAIM 30 (Previously Presented) The method, according to claim 29, wherein providing a texture comprises embossing.

CLAIM 31 (Previously Presented) The method, according to claim 29, wherein providing a texture comprises forming a pit.

CLAIM 32 (Previously Presented) The method, according to claim 29, wherein the embossing comprises forming a raised contact surface.

CLAIM 33 (Previously Presented) The method, according to claim 29, wherein the contact tip structure comprises a surface layer.

CLAIM 34 (Previously Presented) The method, according to claim 33, wherein the contact tip comprises a surface material which in the finished product will form a contact layer of the contact tip structure.

CLAIM 35 (Previously Presented) The method, according to claim 34, wherein the surface material comprises a material suitable for making contact with an electronic component.

CLAIM 36 (Previously Presented) The method, according to claim 34, wherein the surface material comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

CLAIM 37 (Previously Presented) The method, according to claim 33, wherein the contact tip comprises a protuberance.

CLAIM 38 (Previously Presented) The method, according to claim 37, wherein the contact tip comprises gold.

CLAIM 39 (Previously Presented) The method, according to claim 37, wherein the tip material comprises a material selected from the group consisting of Au, Cu, Al, Ag, Ni and combinations thereof.

CLAIM 40 (Previously Presented) The method, according to claim 33, wherein the contact tip comprises a bonding material for joining to the contact tip structure.

CLAIM 41 (Previously Presented) The method, according to claim 40, wherein the bonding material comprises a material suitable for bonding to an interconnection element.

CLAIM 42 (Previously Presented) The method, according to claim 40, wherein the bonding material comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

CLAIM 43 (Previously Presented) The method, according to claim 29, wherein the contact tip structure is formed as an enlarged end.

CLAIM 44 (Previously Presented) The method, according to claim 29, wherein:

the electrical interconnection element is an elongated electrical conductor with a surface layer;

the elongated electrical conductor is readily shaped and comprises a material selected from the group consisting of: gold, aluminum, copper, nickel, palladium, gold alloy and copper alloy.

CLAIM 45 (Previously Presented) The method, according to claim 29, wherein the electrical interconnection is elongate and provides the compliance of the first structure.

CLAIM 46 (Previously Presented) The method, according to claim 45, wherein the interconnection element has a compliant core element and a layer on the core element.

CLAIM 47 (Currently Amended) The method, according to claim 45, wherein the interconnection element has a compliant core element and a layer, on the core element, comprising a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

CLAIM 48 (Previously Presented) The method, according to claim 46, wherein the core element comprises gold.

CLAIM 49 (Previously Presented) The method, according to claim 46, wherein the core element comprises gold and the surface layer comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

CLAIM 50 (Previously Presented) The method, according to claim 46, wherein the layer comprises a material selected from the group consisting of Au, Cr, Co, Ni, Pd and Pt.

CLAIM 51 (Previously Presented) The method, according to claim 46, wherein the layer comprises nickel.

CLAIM 52 (Previously Presented) The method, according to claim 29, wherein said attaching is by a method selected from the group consisting of wire bending, solder bonding, and laser welding.